450ºF - DURALCO™ 4538

Now, unlike ever before, there is a solution for applications requiring the ultimate in thermal shock and vibration resistance, sound absorption and excellent adhesion to dissimilar substrates.

Duralco 4538 offers the flexibility of silicones and the chemical stability of epoxies. This completely variable system can be tailored to meet any application requirement just by varying the mix ratio of resin to hardener resulting in the exact degree of flexibility required for any application.

It's easy to use. Just dispense resin and hardener, mix to a uniform color and apply.

Adheres to most plastics, metals, ceramics, glass, rubber and even Teflon™ (treated).

Cures at room temperature for use from -100°F to +450°F and will not soften or gum up at high temperatures.

Duralco 4538 offers excellent chemical resistance and high bond and peel strength.

It is ideal for all electric and electronics applications and can be used with most common chemicals and solvents.

Users Report:

Bonds: Zytel™ 101, Victrex™, Poly-Phenylsulfone, Nylon, Poly-Carbonates, Phenolics and other difficult materials. Successfully bonds a Teflon™ housing to a Ceramic Bushing, Ceramic magnets to a plastics holder.

Thermal Shock Resistance: Withstands repeated thermal cycling from -100°F to +300°F.

Seals: Bonded and sealed a 4 inch diameter glass sight port to a brass housing for use from -100°F to +300°F.

Encapsulates: Stress free potting of delicate electronic assemblies for severe thermal shock environments.

High Peel Strength: Adheres to Teflon™ (treated) and other hard to bond plastics.

Duralco 4538's convenient room temperature cure and superior high temperature performance makes it easy to use in any prototype or production application.

Adjusting the Flexibility

Just pick the degree of flexibility desired.

Then select the resin to hardener ratio from the table.

- Use formulation "A" for applications where additional rigidity is required.
- Use formulation "B" for most applications.
- Use formulation "C" or "D" for severe thermal shock, vibration or bonding of dissimilar materials that require additional flexibility.